

Application Serial No: 10/593,674
Responsive to the Office Action mailed on: November 25, 2008

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IN THE CLAIMS

Amendments To The Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A chip resistor comprising:
a chip-like resistor element including a bottom surface, an upper surface opposite to the bottom surface, two end surfaces and two side surfaces;
~~two~~ a plurality of electrodes spaced from each other on the bottom surface of the resistor element; and
an insulator between the ~~two~~ electrodes;
wherein at least one of the ~~two~~ electrodes ~~overlaps~~ includes a non-overlapping portion held in direct contact with the bottom surface of the resistor element and an overlapping portion laminated over the insulator at a position away from the bottom surface of the resistor element, the overlapping portion including a flat mounting surface extending in parallel to the bottom surface of the resistor element, as viewed in a direction in which the bottom surface and the upper surface are spaced from each other.
2. (Currently Amended) The chip resistor according to claim 1, wherein the insulator is a resin film which is flat as a whole, and said at least one of the electrodes including an overlapping portion extending onto the resin film.
3. (Currently Amended) The chip resistor according to claim 1, wherein ~~the insulator includes a first portion between the two electrodes, and a second portion formed integral with the first portion, the second portion extending on said~~ at least one of the electrodes includes a first conductive layer partially covering the bottom surface of the resistor element and the insulator, said at least one of the electrodes also including a second conductive layer covering the first conductive layer, a portion of the second conductive layer located in the non-overlapping portion being wider than the first conductive layer.

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4. (Original) The chip resistor according to claim 1, further comprising a soldering-facilitation layer which covers the end surfaces of the resistor element and the electrodes.

5. (Original) The chip resistor according to claim 1, further comprising an additional insulation film formed on the upper surface of the resistor element, and two auxiliary electrodes spaced from each other via the additional insulation film.

Claims 6-12. (Cancelled)

13. (New) The chip resistor according to claim 1, wherein said at least one of the electrodes includes a first conductive layer partially covering the bottom surface of the resistor element and the insulator, said at least one of the electrodes also including a second conductive layer covering the first conductive layer, the second conductive layer extending up to one of the end surfaces of the resistor element, the first conductive layer being spaced from said one of the end surfaces of the resistor element.

14. (New) The chip resistor according to claim 1, wherein said at least one of the electrodes includes a first conductive layer partially covering the bottom surface of the resistor element and the insulator, said at least one of the electrodes also including a second conductive layer covering the first conductive layer, the first conductive layer including a first area covering the resistor element and a second area covering the insulator, the second area being larger than the first area.

15. (New) A chip resistor comprising:

a chip-like resistor element including a bottom surface, an upper surface opposite to the bottom surface, two end surfaces and two side surfaces;

a plurality of electrodes spaced from each other on the bottom surface of the resistor element; and

an insulator between the electrodes;

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wherein the insulator includes a first portion between the electrodes, and a second portion formed integral with the first portion and laminated over each of the electrodes at a position away from the bottom surface of the resistor element.

16. (New) The chip resistor according to claim 15, further comprising a soldering-facilitation layer which covers the end surfaces of the resistor element and the electrodes.

17. (New) The chip resistor according to claim 15, further comprising an insulation film formed on the upper surface of the resistor element, and two auxiliary electrodes spaced from each other via the insulation film.